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TITLE: METHODS FOR REDUCING DELAMINATION DURING
CHEMICAL MECHANICAL POLISHING
INVENTOR: YUFEI CHEN, ET AL.
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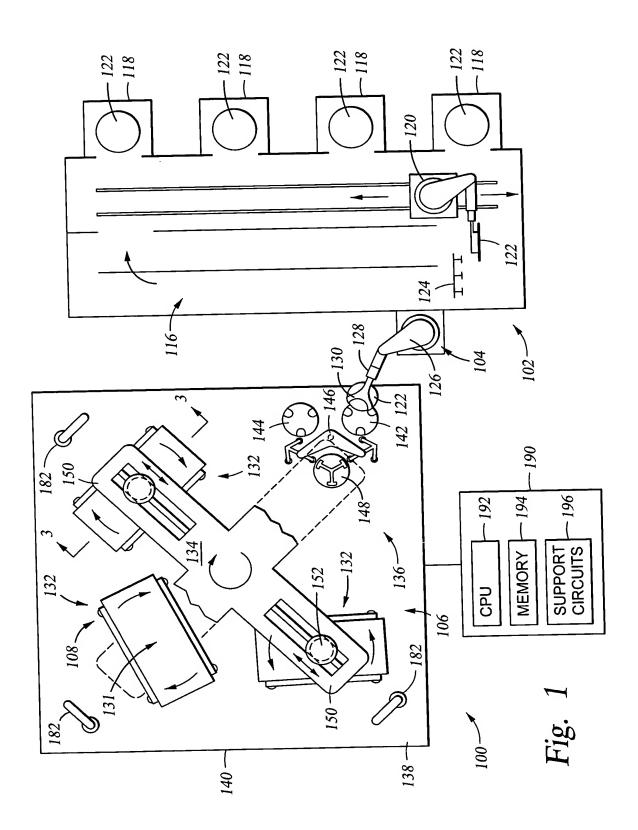
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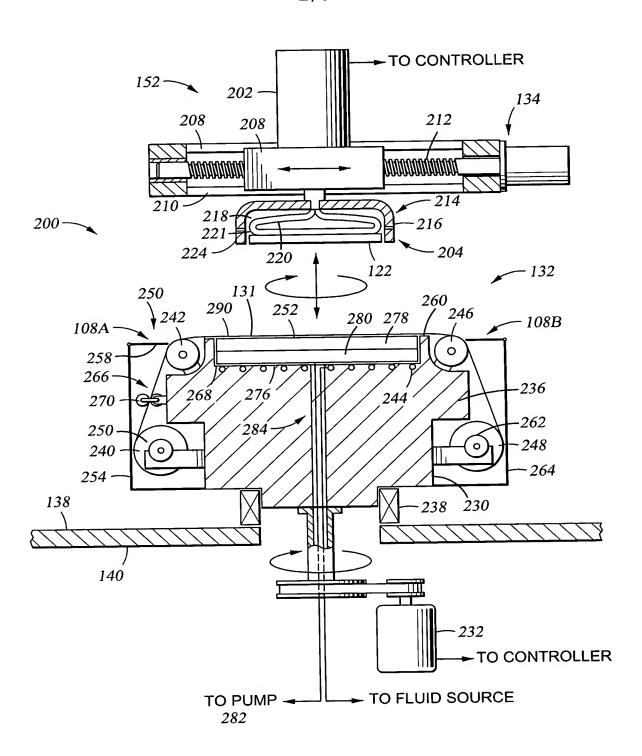


Fig. 2

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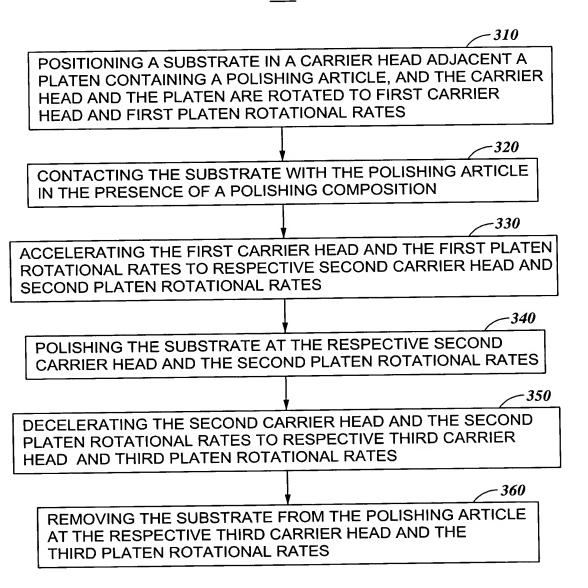


Fig. 3